OSRAM LT Y1SG

Datasheet

Published by ams-OSRAM AG
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OSRAM

Micro SIDELED® 2808

LT Y1SG

Micro SIDELED is a SMT LED with side emission. Due to its low package height it is ideal for applications in limited space environments.

Applications

- Electronic Equipment
- White Goods

Features

- Package: white SMT package, colorless clear resin
- Chip technology: InGaN on Sapphire
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 523 nm (● true green)
- Optical efficacy: 112 lm/W
- Corrosion Robustness Class: 1B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity [1] I_F = 20 mA I_v	Ordering Code
LT Y1SG-BACB-35-1	1800 ... 4500 mcd	Q65113A3905

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 85 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T_j	max.	95 °C
Forward current T_A = 25 °C	I_F	min. max.	5 mA 30 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_A = 25 °C	I_{FS}	max.	300 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV
Reverse voltage [2)]	V_R		Not designed for reverse operation

Characteristics

I_F = 20 mA; T_A = 25 °C

Parameter	Symbol		Values
Dominant Wavelength [3]	λ_{dom}	min. typ. max.	519 nm 523 nm 537 nm
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [4] I_F = 20 mA	V_F	min. typ. max.	2.40 V 2.85 V 3.20 V
Reverse current [2]	I_R		Not designed for reverse operation
Real thermal resistance junction/solderpoint [5]	$R_{thJS\ real}$	typ. max.	125 K / W 150 K / W
Electrical thermal resistance junction/solderpoint [5] with efficiency η_e = 28 %	$R_{thJS\ elec.}$	typ. max.	90 K / W 108 K / W

Brightness Groups

Group	Luminous Intensity [1] I_F = 20 mA min. I_v	Luminous Intensity. [1] I_F = 20 mA max. I_v	Luminous Flux [6] I_F = 20 mA typ. Φ_V
BA	1800 mcd	2240 mcd	6060 mlm
BB	2240 mcd	2800 mcd	7560 mlm
CA	2800 mcd	3550 mcd	9530 mlm
CB	3550 mcd	4500 mcd	12080 mlm

Forward Voltage Groups

Group	Forward Voltage [4] I_F = 20 mA min. V_F	Forward Voltage [4] I_F = 20 mA max. V_F
J	2.40 V	2.60 V
K	2.60 V	2.80 V
L	2.80 V	3.00 V
M	3.00 V	3.20 V

Wavelength Groups

Group	Dominant Wavelength [3] min. λ_{dom}	Dominant Wavelength [3] max. λ_{dom}
3	519 nm	525 nm
4	525 nm	531 nm
5	531 nm	537 nm

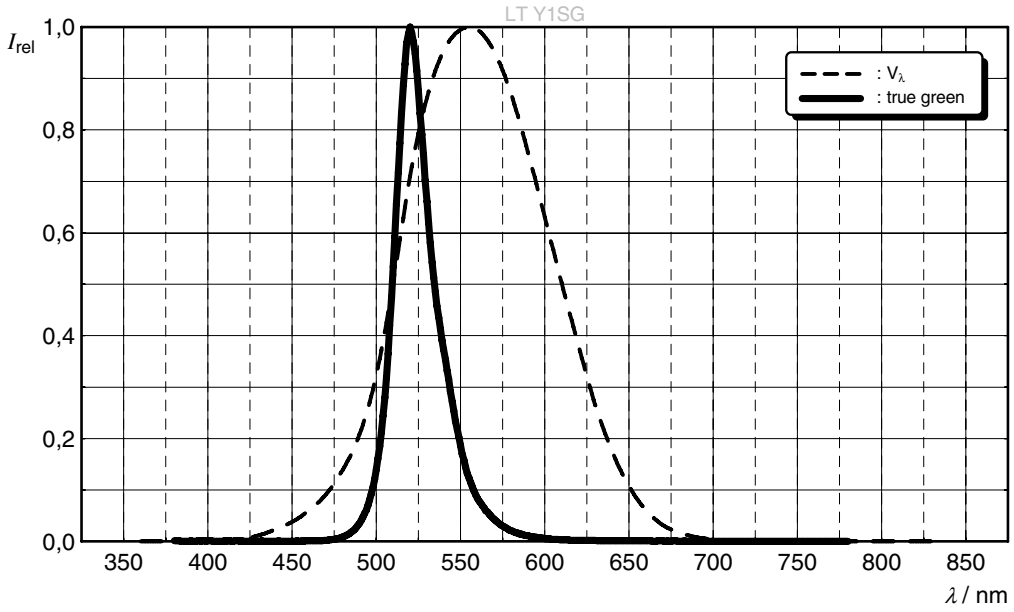
Group Name on Label

Example: BA-3-J

Brightness	Wavelength	Forward Voltage
BA	3	J

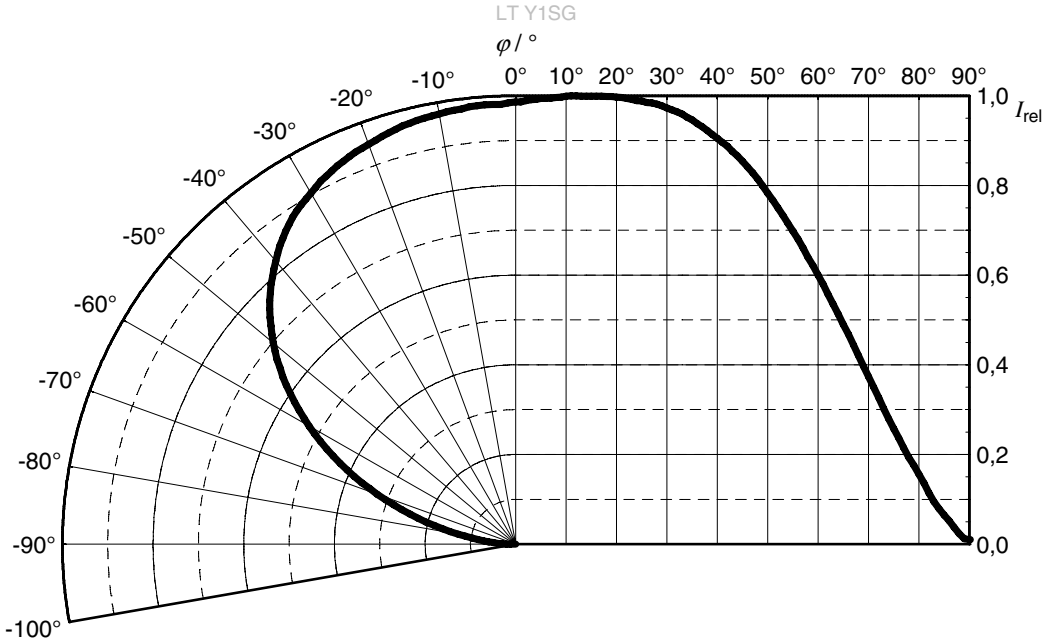
Relative Spectral Emission [6)]

$I_{rel} = f(\lambda)$; $I_F = 20$ mA; $T_A = 25$ °C



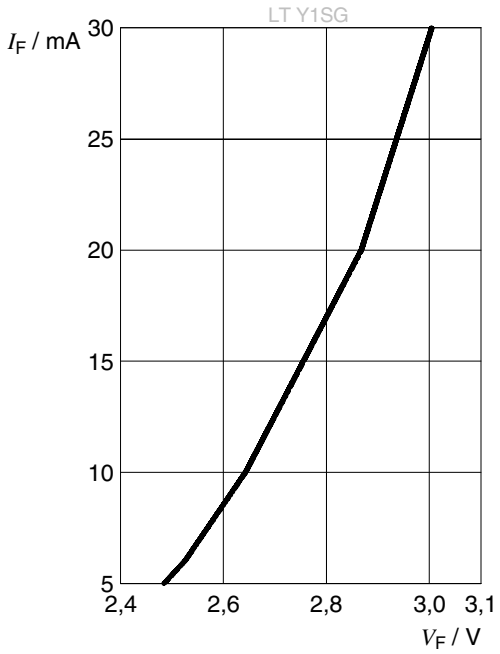
Radiation Characteristics [6)]

$I_{rel} = f(\phi)$; $T_A = 25$ °C



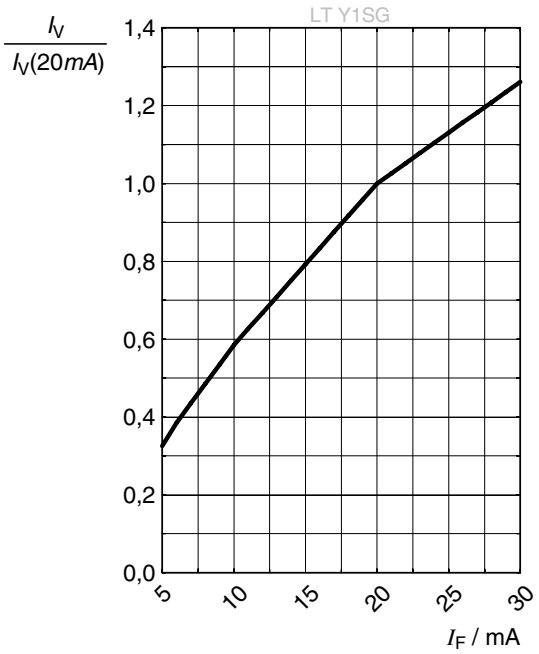
Forward current [6)]

$I_F = f(V_F)$; T_A = 25 °C



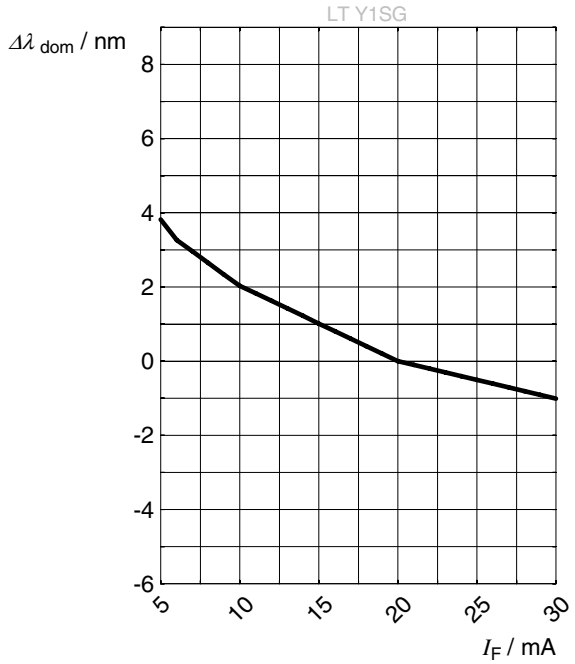
Relative Luminous Intensity [6), 7)]

$I_v/I_v(20\ mA) = f(I_F)$; T_A = 25 °C



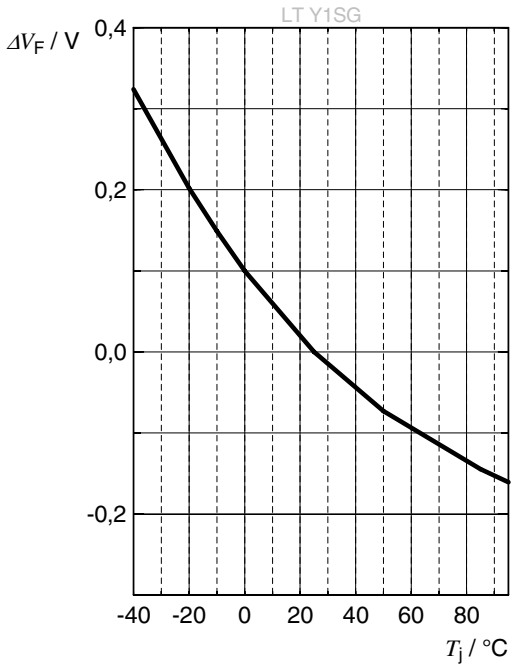
Dominant Wavelength [6)]

$\Delta\lambda_{dom} = f(I_F)$; T_A = 25 °C



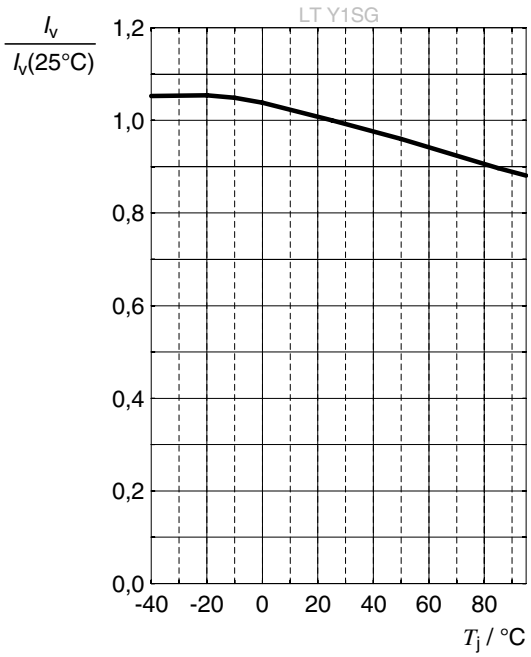
Forward Voltage [6)]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j)$; $I_F = 20$ mA



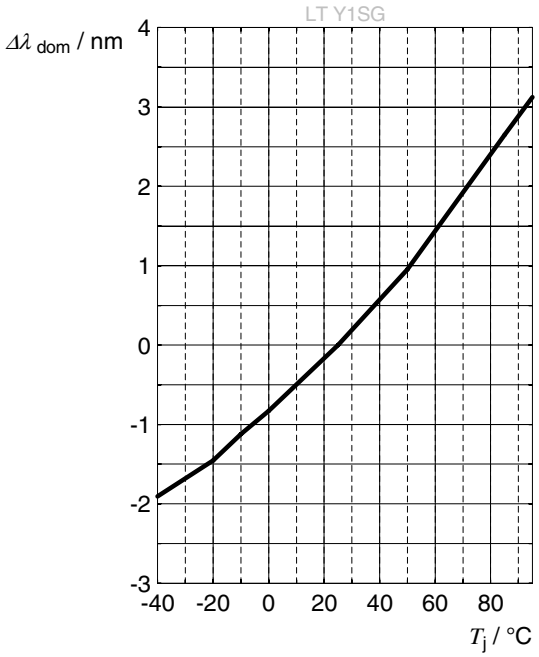
Relative Luminous Intensity [6)]

$I_v/I_v(25\ °C) = f(T_j)$; $I_F = 20$ mA



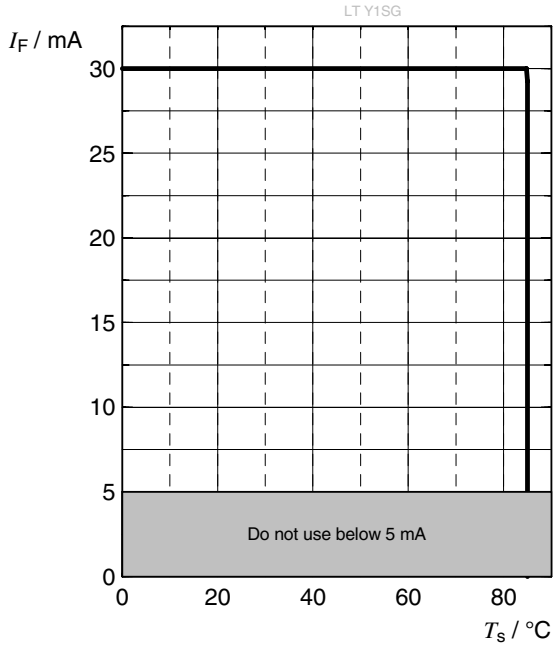
Dominant Wavelength [6)]

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}(25\ °C) = f(T_j)$; $I_F = 20$ mA



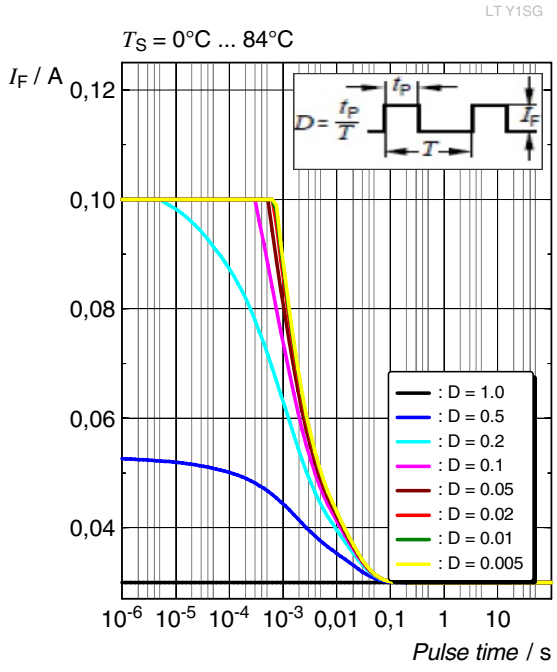
Max. Permissible Forward Current

$I_F = f(T)$



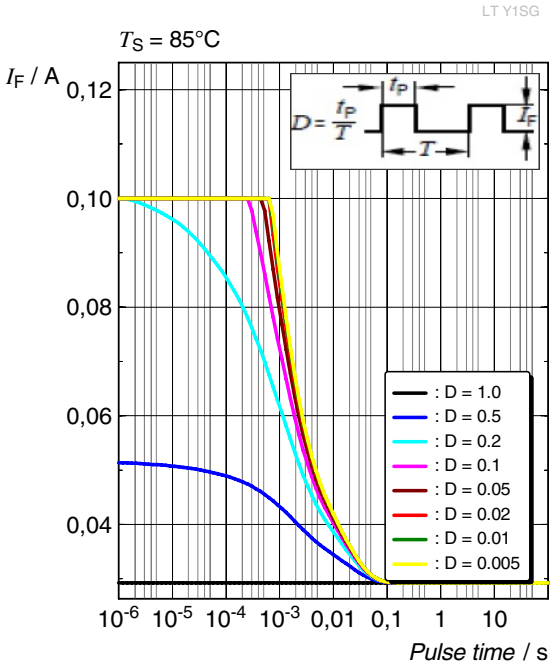
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_A = 25 °C

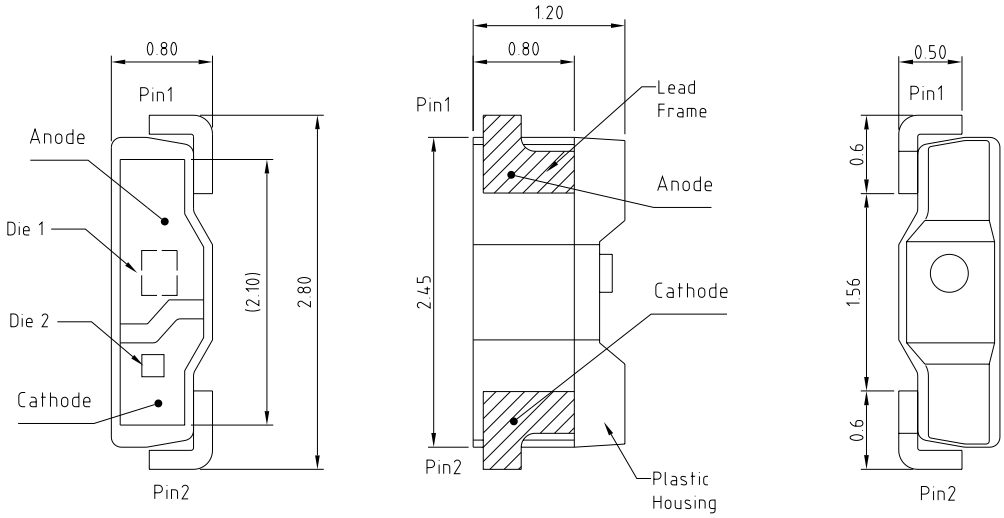


Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_A = 85 °C



Dimensional Drawing [8)]



General tolerance ± 0.1
lead finish Ag

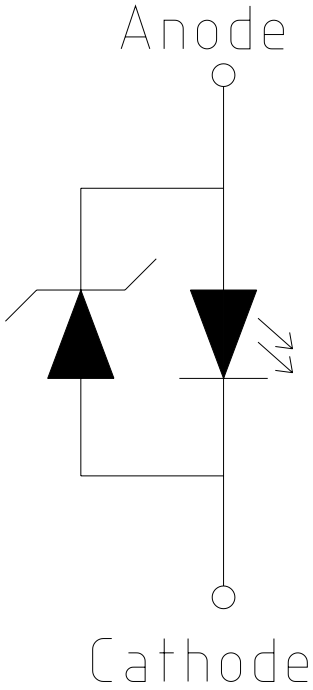
C67062-A0424-A1-01

Further Information:

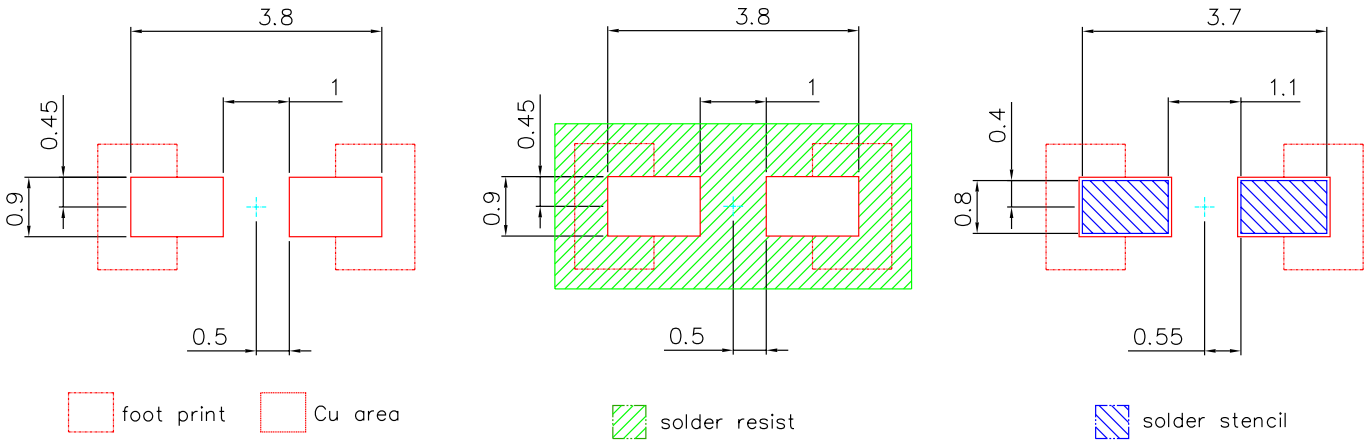
Approximate Weight: 5.0 mg

Corrosion test: Class: 1B
Test condition: 25°C / 75 % RH / 200ppb SO_2, 200ppb NO_2, 10ppb H_2S, 10ppb Cl_2 / 21 days (EN 60068-2-60 (Method 4))

Electrical Internal Circuit



Recommended Solder Pad [8)]

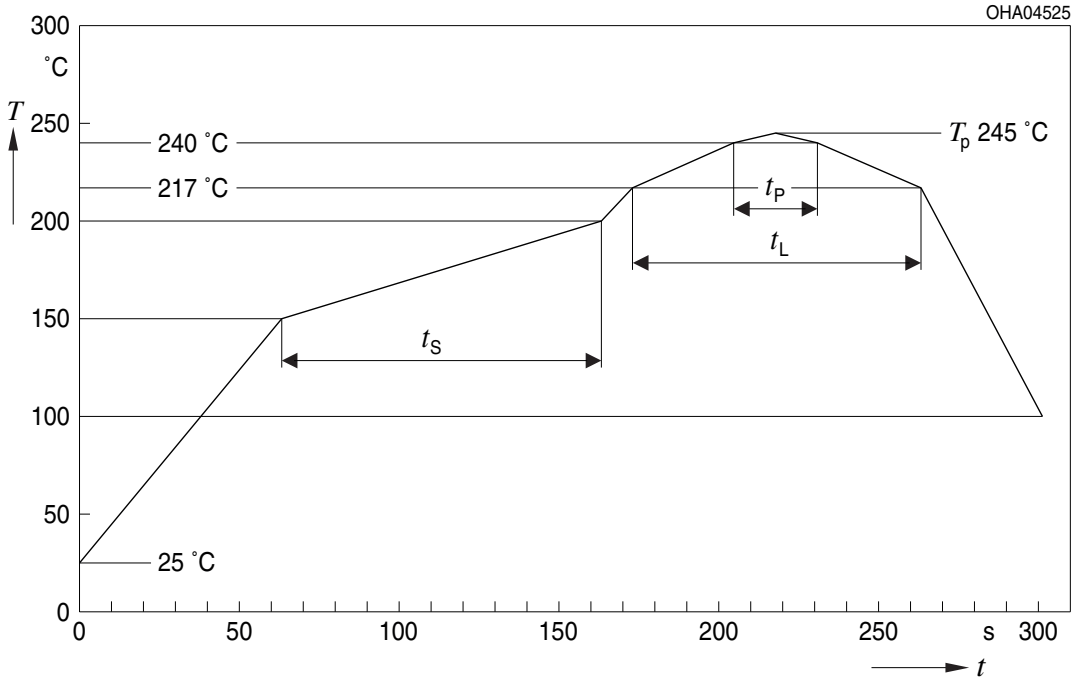


E067.0346.21–01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

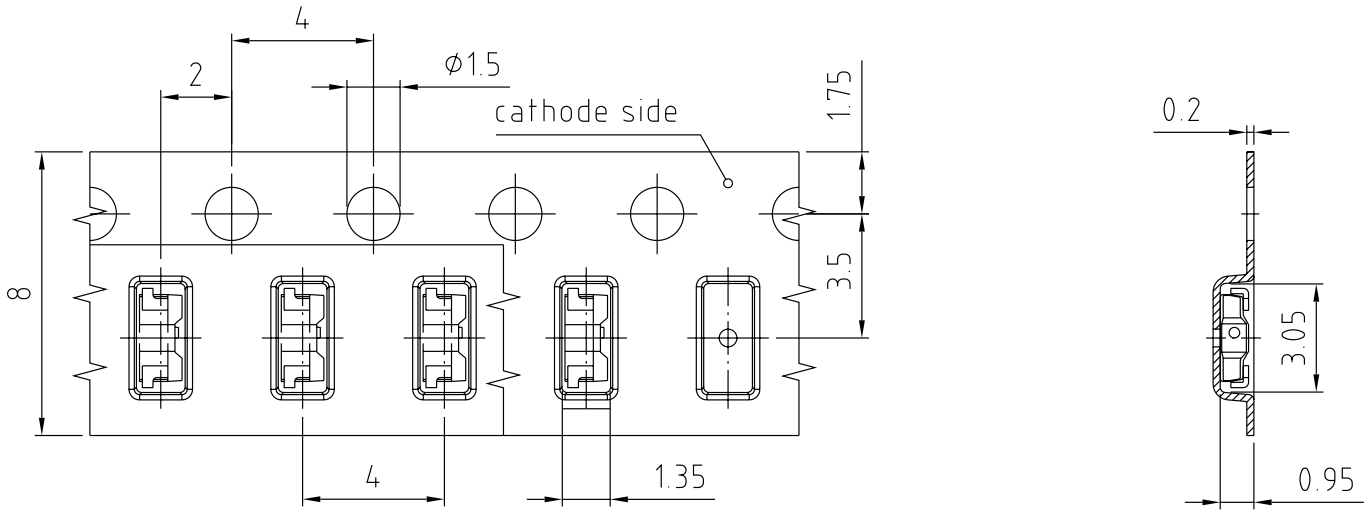
Product complies to MSL Level 4 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [8)]



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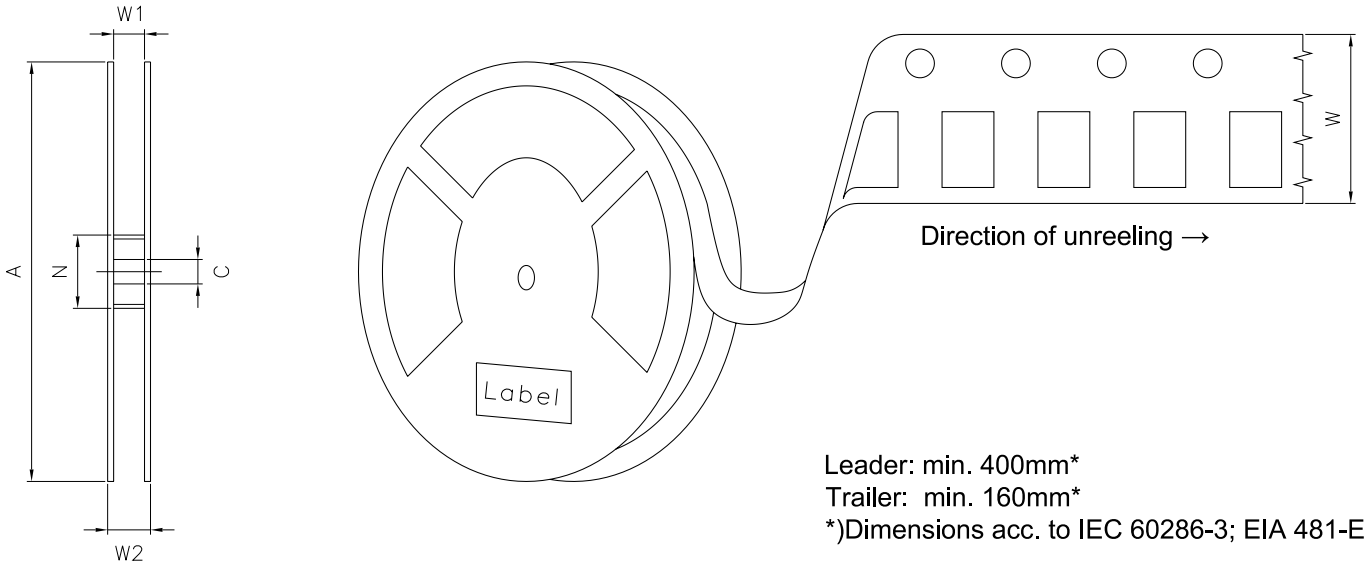
Tape and Reel [9)]

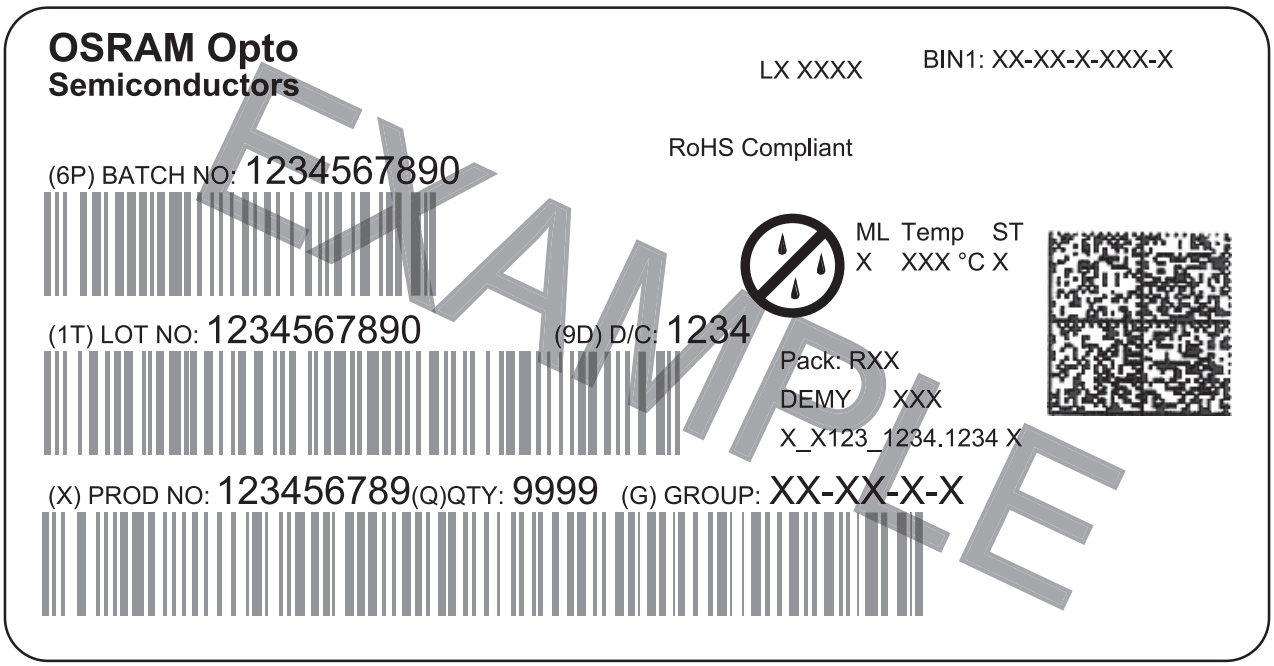


Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

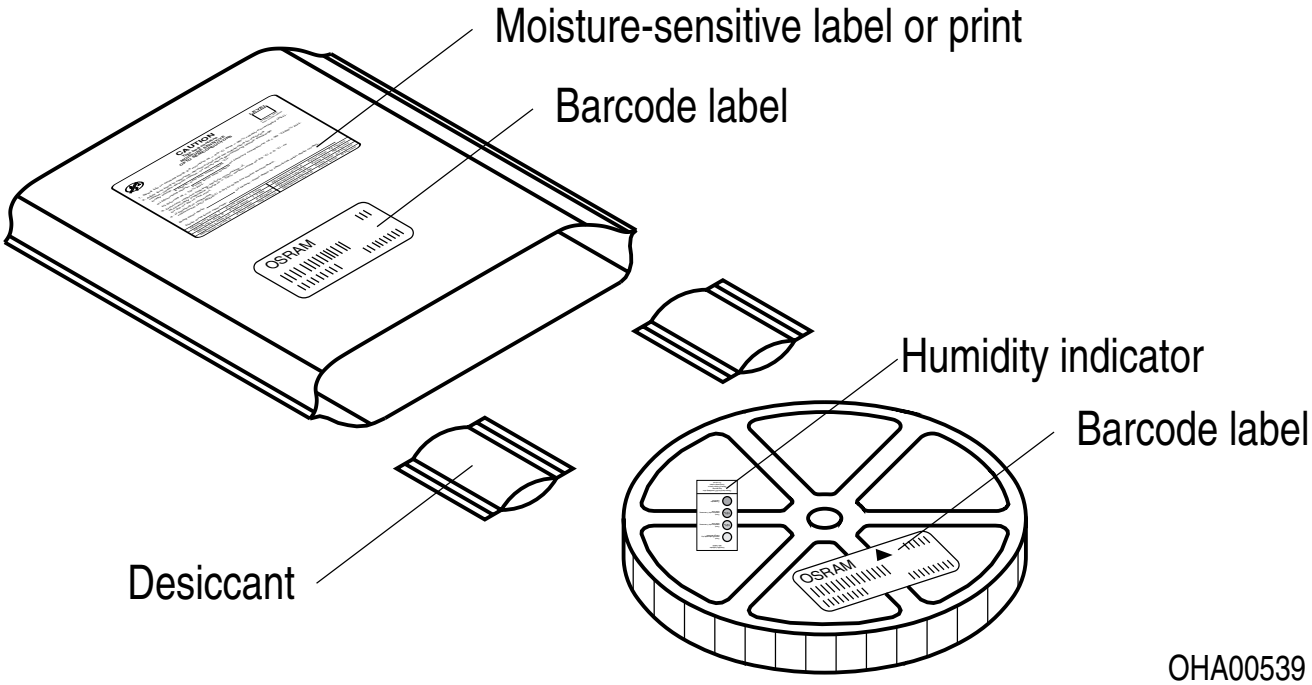
A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000

Barcode-Product-Label (BPL)



OHA04563

Dry Packing Process and Materials [8)]



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.
Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

1) **Brightness:** Brightness groups are tested at a current pulse duration of 25 ms and a tolerance of ±11 %.

2) **Reverse Operation:** Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.

3) **Wavelength:** Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of ±1 nm.

4) **Forward Voltage:** Forward voltages are tested at a current pulse duration of 1 ms and a tolerance of ±0.1 V.

5) **Thermal Resistance:** Rth max is based on statistic values (6σ).

6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.0	2021-09-20	Initial Version
1.1	2022-03-17	New Layout Derating (Diagrams)

EU RoHS and China RoHS compliant product
此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，
不含有毒有害物质或元素。

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